

TITLE: SEMICONDUCTOR SUBSTRATES INCLUDING I/O
REDISTRIBUTION USING WIRE BONDS AND ANISOTROPICALLY
CONDUCTIVE FILM, METHODS OF FABRICATION AND
ASSEMBLIES INCLUDING SAME

Inventor: Lu et al.
Docket No.: 2269-5709US

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1/10

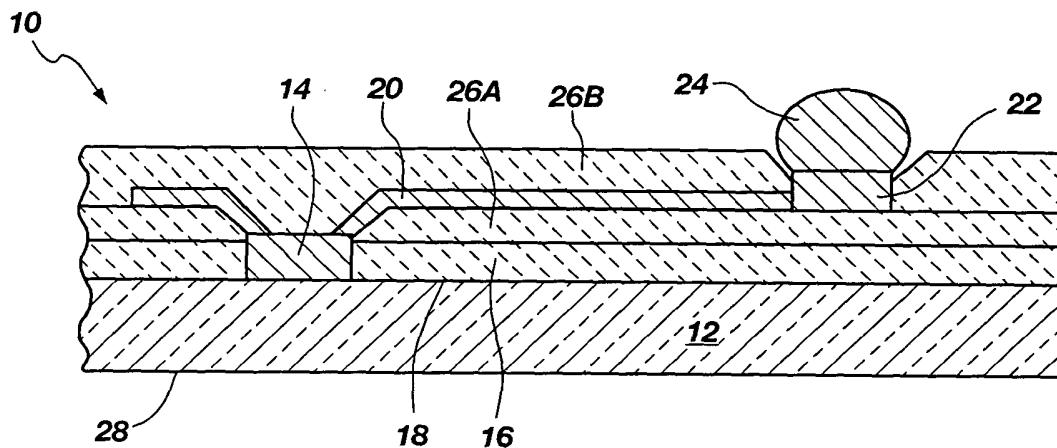


FIG. 1
(PRIOR ART)

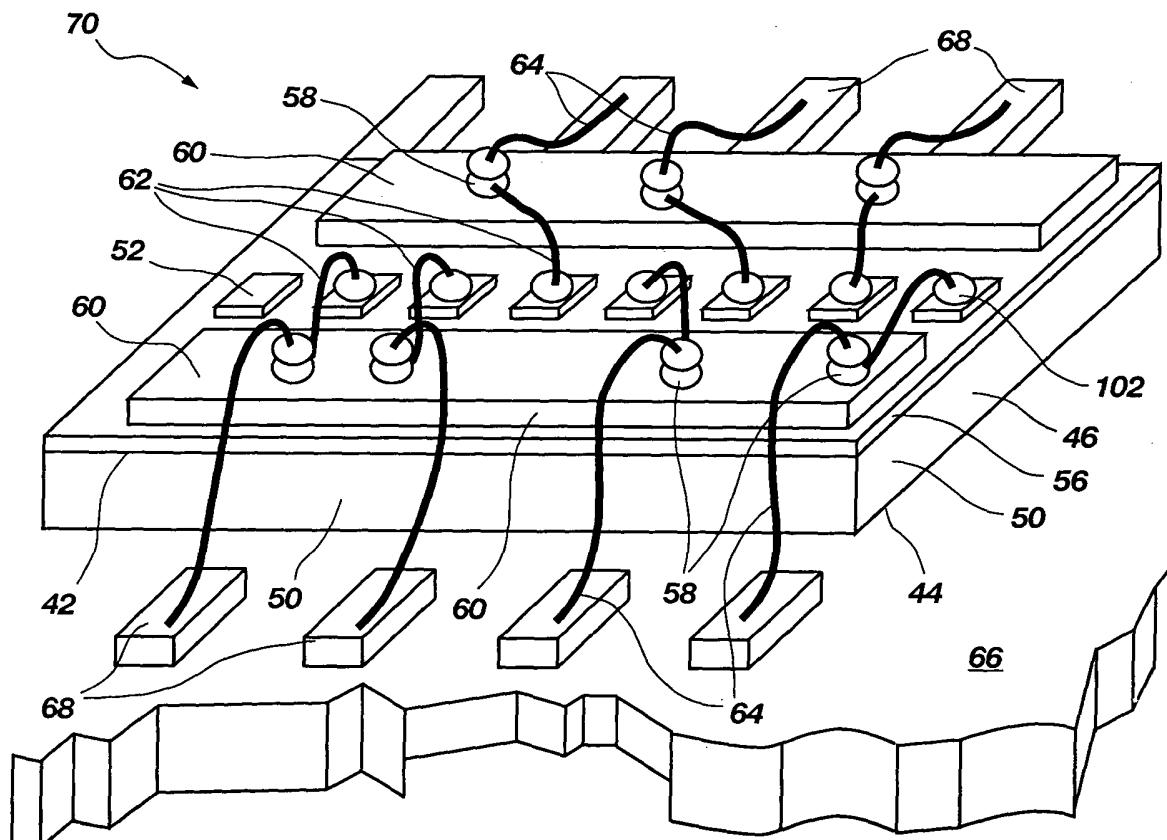


FIG. 12

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2/10

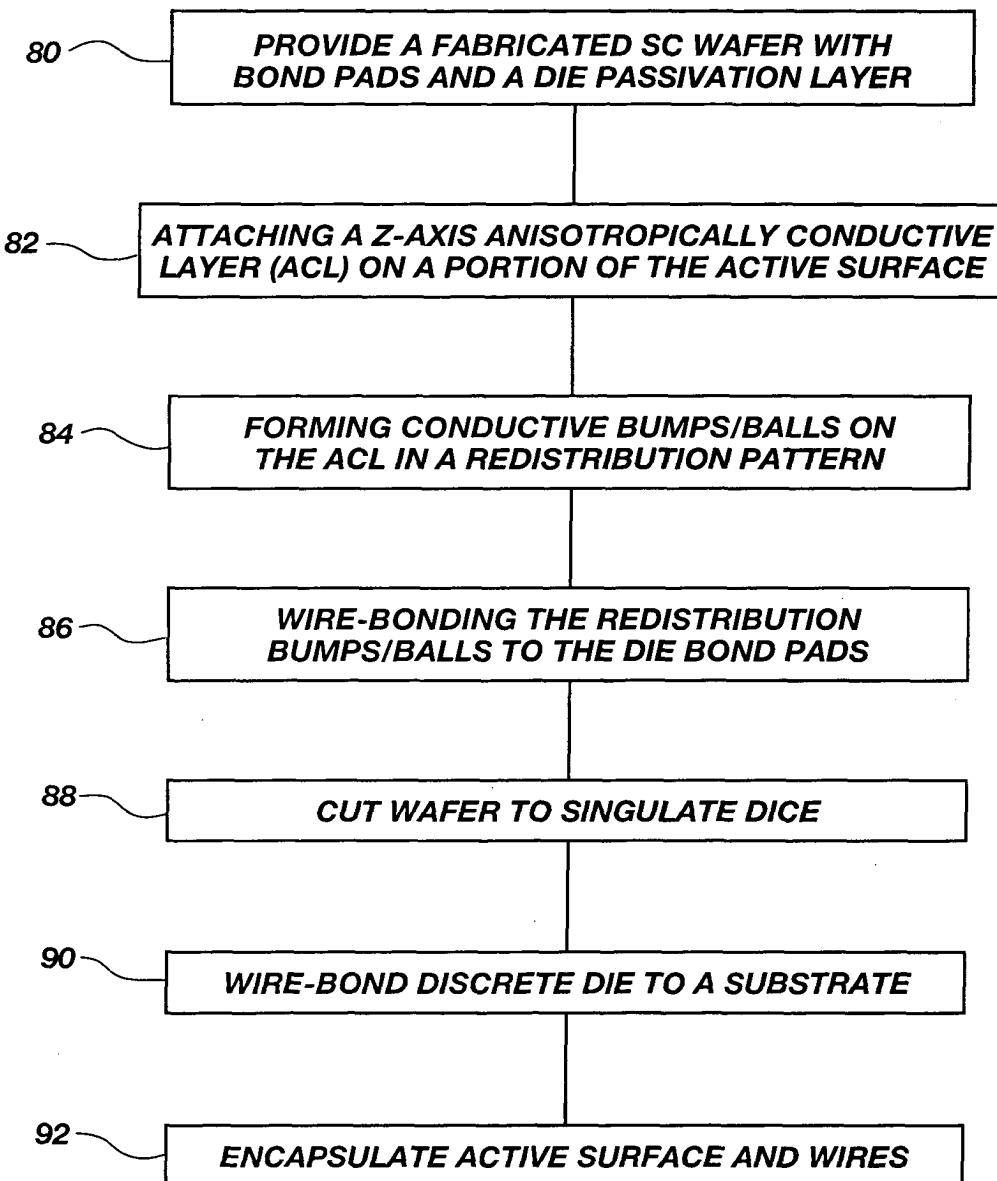


FIG. 2

TITLE: SEMICONDUCTOR SUBSTRATES INCLUDING I/O
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3/10

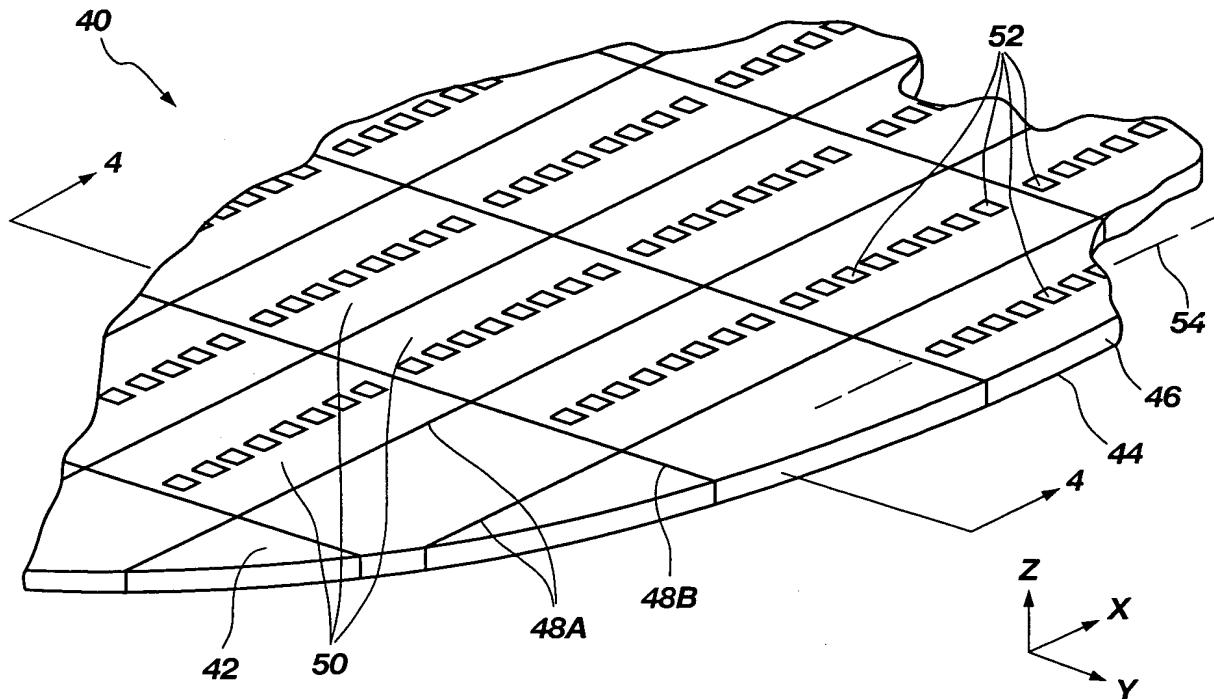


FIG. 3

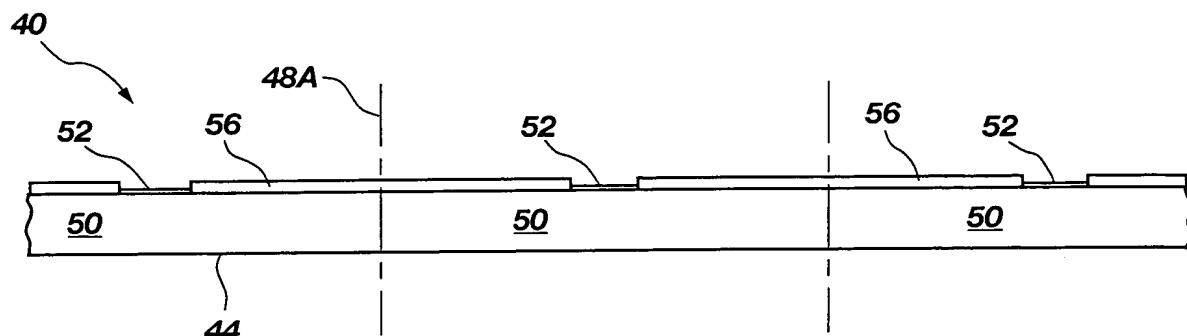


FIG. 4

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4/10

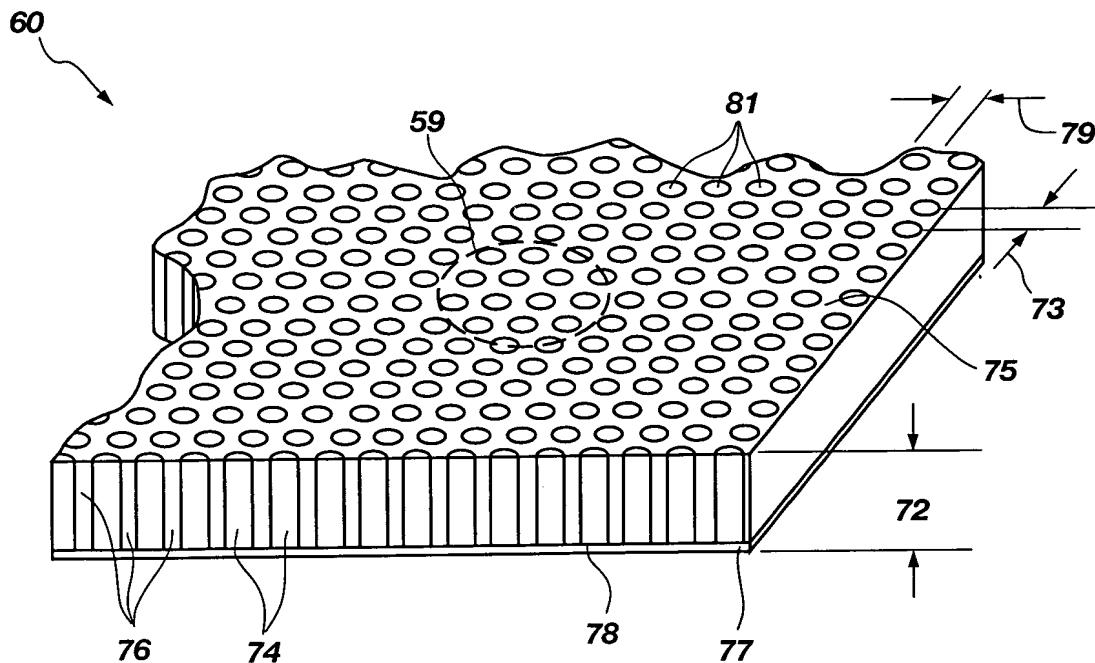


FIG. 5

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5/10

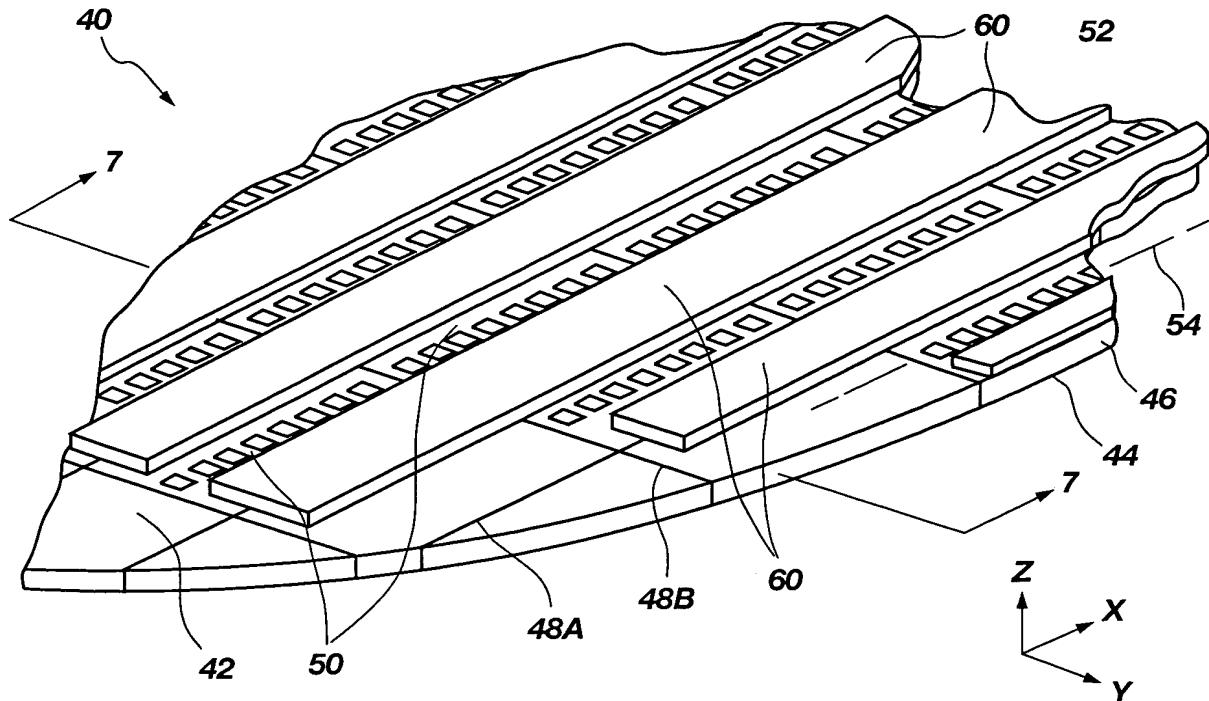


FIG. 6

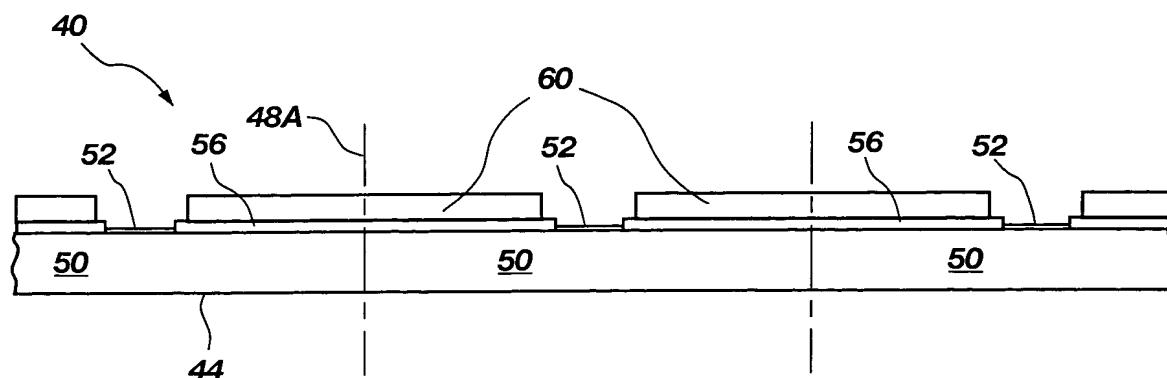


FIG. 7

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6/10

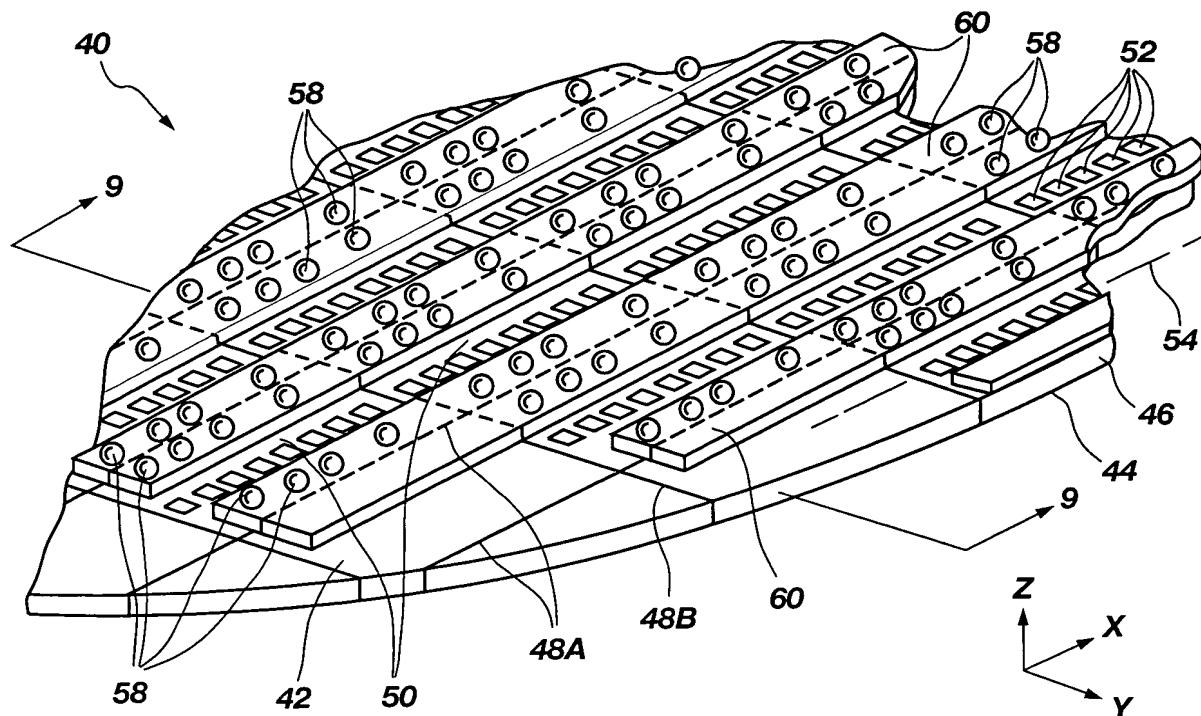


FIG. 8

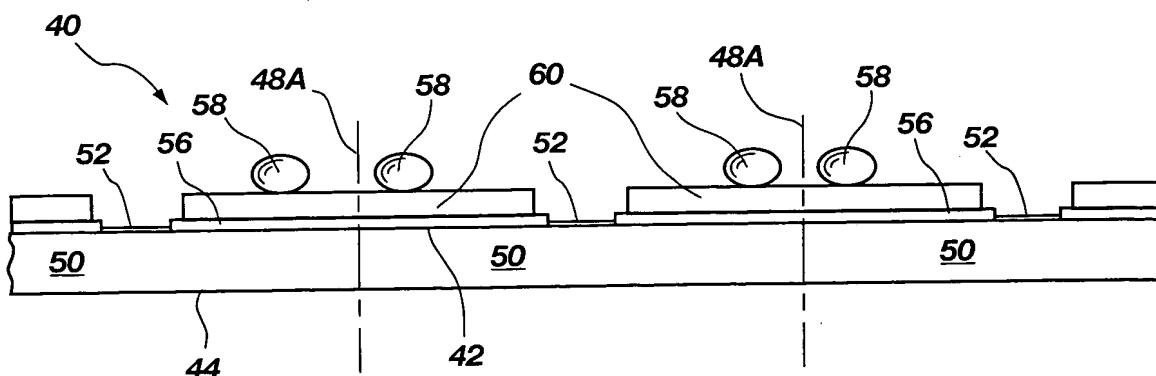


FIG. 9

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8/10

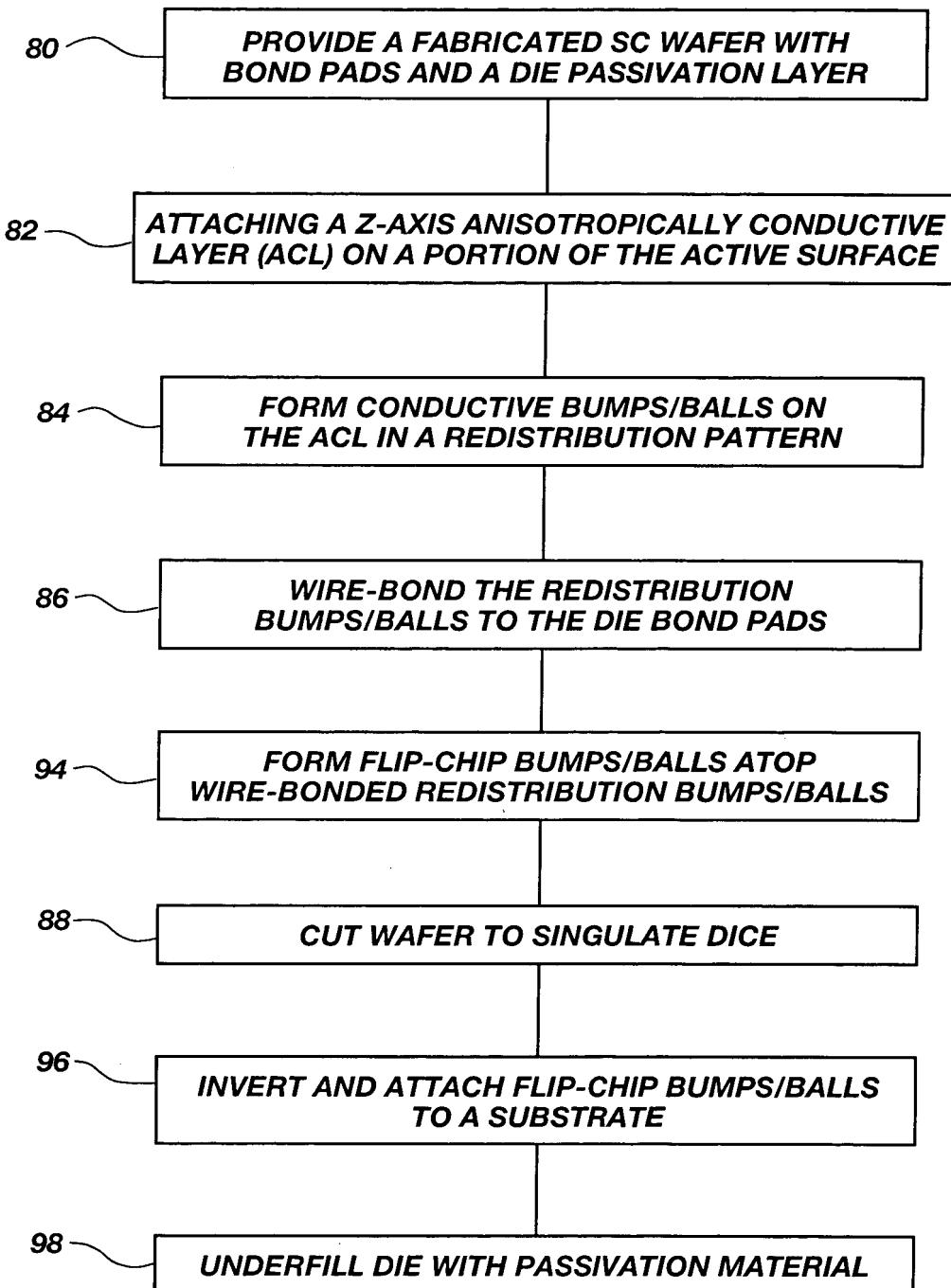


FIG. 13

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10/10

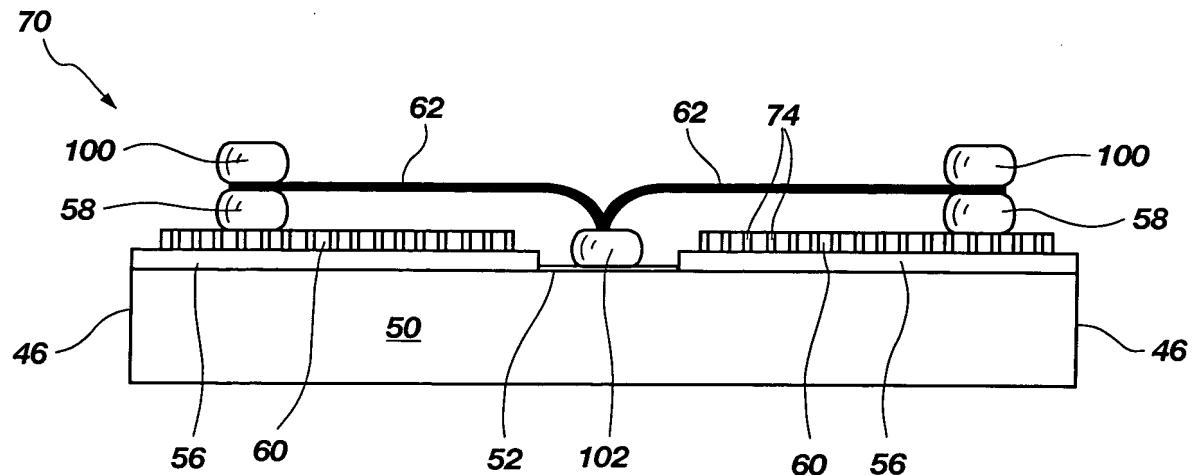


FIG. 16

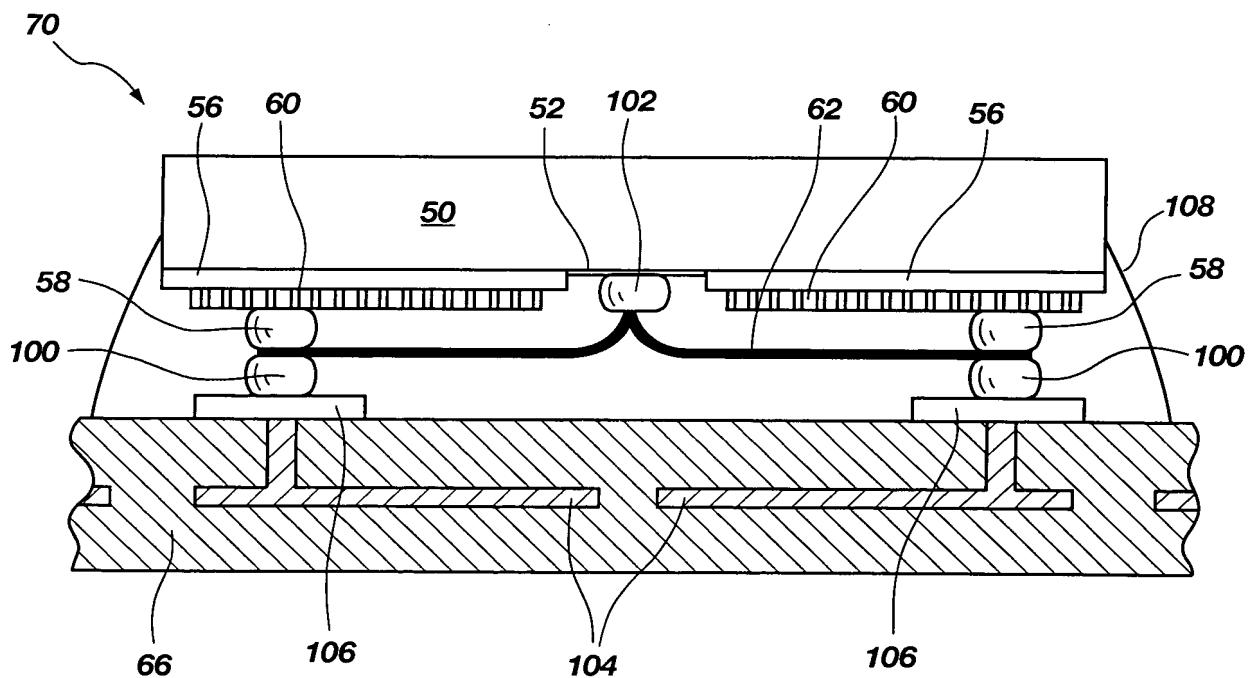


FIG. 17